

Page i

# TRANSISTORS, LOW POWER, NPN, BASED ON TYPES 2N3498, 2N3499, 2N3500 AND 2N3501

**ESCC Detail Specification No. 5201/013** 

# ISSUE 1 October 2002





#### **ESCC Detail Specification**

PAGE	ii
ISSUE	1

#### **LEGAL DISCLAIMER AND COPYRIGHT**

European Space Agency, Copyright © 2002. All rights reserved.

The European Space Agency disclaims any liability or responsibility, to any person or entity, with respect to any loss or damage caused, or allleged to be caused, directly or indirectly by the use and application of this ESCC publication.

This publication, without the prior permission of the European Space Ageny and provided that it is not used for a commercial purpose, may be:

- copied in whole in any medium without alteration or modification.
- copied in part, in any medium, provided that the ESCC document identification, comprising the ESCC symbol, document number and document issue, is removed.



# european space agency agence spatiale européenne

Pages 1 to 21

# TRANSISTORS, LOW POWER, NPN, BASED ON TYPES 2N3498, 2N3499, 2N3500 AND 2N3501

ESA/SCC Detail Specification No. 5201/013



# space components coordination group

	Approved by		
Date	SCCG Chairman	ESA Director Genera or his Deputy	
March 1995	Tomoreus	Journ	
November 1995	Tonomens	Hoom	
	March 1995	Date SCCG Chairman  March 1995	



PAGE 2

ISSUE 4

# **DOCUMENTATION CHANGE NOTICE**

DOCUMENTATION CITATION CITATIO					
Rev.	Rev.		CHANGE	Approved	
Letter	Date	Reference	Item	DCR No.	
201101		, .0.0.		_	
		This Issue superse	edes Issue 3 and incorporates all modifications defined in		
			nd 'C' to Issue 3 and the following DCR's:-		
		Cover page		None	
		DCN		None	
		Para. 1.2	: Text inserted	23721	
		Table 1(a)	: Variants 11 and 12 added	221156	
		Table 1(b)	: Nos. 1, 2, 4, in Characteristics, "11, 12" added to 05,	221156	
			06, 07, 08		
			: No. 5, in Remarks, "T <sub>amb</sub> " added	221156	
			: No. 6, in Remarks, "T <sub>case</sub> " added	221156	
			: No. 7, Symbol amended and "T <sub>amb</sub> " added to Remarks	23721	
1		Figures 2(a), (b)	: Imperial Dimensions deleted from Table and Notes	23721	
1		Para. 2	: Item (c) deleted	23721	
		Para. 4.2.3	: "Para. 7.1.1" added to text	23721	
		Para. 4.5.1	: Text deleted and new text added	23721	
		Para. 4.5.3	: "(see Table 1(a))" added to Type Variant	23721	
1		Para. 4.5.5	: Deleted in toto	23721	
		Para. 4.6.1	: "Unless otherwise specified" added to second sentence	23721	
		Para. 4.7.2	: New Title and reference added	23721	
			: Original paragraph renumbered and Title and text amended	23721	
i		Para. 4.7.3	: Renumbered as "4.7.5" and Title and text amended	23721	
		Para. 4.7.4	: New Title and reference added	23721	
	İ	Table 2 d.c.	: Nos. 1, 2, 4, 9, 11, in Conditions, "11, 12" added to 05,	221156	
		14010 2 0.0.	06, 07, 08		
			: Nos. 6, 7, in Conditions, Variants amended	221156	
			: No. 8, in Conditions, Variants amended and "11, 12" added	221156	
			: Nos. 10, 12, in Conditions, Variants deleted	221156	
			: Nos. 11, 12, Characteristics corrected	23721	
		Table 2 a.c.	: Nos. 14, 18, 20, in Conditions, "11, 12" added to 05, 06, 07, 08	221156	
			: No. 15, in Conditions, Variants amended	221156	
1		Table 3	: No. 4, in Conditions, "11, 12" added to 05, 06, 07, 08	221156	
1			: No. 7, in Conditions, Variants amended	221156	
1		Table 5(a)	: Title and reference added	23721	
		Table 5	: Title amended	23721	
1		1	: No. 3, in Characteristics, "11, 12" added to 05, 06, 07,	221156	
			08 and Variants moved to Conditions column		
1		Figure 5(a)	: Title and reference added	23721	
		Figure 5	: Title amended	23721	
		Para. 4.8.1	: Second sentence completed	23721	
		Para. 4.8.2	: Second sentence added	23721	
		Table 6	: Nos. 4, 9, in Characteristics, "11, 12" added to 05, 06,	221156	
			07, 08 and Variants moved to Test Conditions column	1	
			: No. 7, in Characteristics, Variants amended and moved to Test Conditions column	221156	
		1			
1		<b>!</b>			



Rev. 'A'

PAGE 2A

ISSUE 4

# **DOCUMENTATION CHANGE NOTICE**

Rev. Letter	Rev. Date	Reference	CHANGE Item	Approved DCR No.
		P1. Cover page P2A. DCN P3. T of C		Approved DCR No.  None None 21083 21083



Rev. 'A'

PAGE 3

ISSUE 4

# **TABLE OF CONTENTS**

1.	GENERAL	Page 5
1.1	Scope	5
1.2	Component Type Variants	5
1.3	Maximum Ratings	5
1.4	Parameter Derating Information	5
1.5	Physical Dimensions	5
1.6	Functional Diagram	5
1.7	High Temperature Test Precautions	5
2.	APPLICABLE DOCUMENTS	5
3.	TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS	, 5
4.	REQUIREMENTS	11
4.1	General	11
4.2	Deviations from Generic Specification	11
4.2.1	Deviations from Special In-process Controls	11
4.2.2	Deviations from Final Production Tests	11
4.2.3	Deviations from Burn-in Tests	11
4.2.4	Deviations from Qualification Tests	11
4.2.5	Deviations from Lot Acceptance Tests	11
4.3	Mechanical Requirements	11
4.3.1	Dimension Check	11
4.3.2	Weight	11
4.3.3	Terminal Strength	11
4.4	Materials and Finishes	11 12
4.4.1 4.4.2	Case Lead Material and Finish	12
		12
4.5 4.5.1	Marking General	12
4.5.1	Lead Identification	12
4.5.2	The SCC Component Number	12
4.5.4	Traceability Information	12
4.6	Electrical Measurements	12
4.6.1	Electrical Measurements at Room Temperature	12
4.6.2	Electrical Measurements at High and Low Temperatures	12
4.6.3	Circuits for Electrical Measurements	13
4.7	Burn-in Tests	13
4.7.1	Parameter Drift Values	13
4.7.2	Conditions for High Temperature Reverse Bias Burn-in	13
4.7.3	Conditions for Power Burn-in	13
4.7.4	Electrical Circuits for High Temperature Reverse Bias Burn-in	13
4.7.5	Electrical Circuits Power for Burn-in	13
4.8	Environmental and Endurance Tests	20
4.8.1	Electrical Measurements on Completion of Environmental Tests	20
4.8.2	Electrical Measurements at Intermediate Points and on Completion of Endurance Tests	20
4.8.3	Conditions for Operating Life Tests	20
4.8.4	Electrical Circuits for Operating Life Tests	20
4.8.5	Conditions for High Temperature Storage Test	20



PAGE 4

ISSUE 4

		Page
TABLE	<u>:S</u>	
1(a)	Component Type Variants	6
1(b)	Maximum Ratings	6
2 ′	Electrical Measurements at Room Temperature - d.c. Parameters	14
	Electrical Measurements at Room Temperature - a.c. Parameters	16
3	Electrical Measurements at High and Low Temperatures	17
4	Parameter Drift Values	19
5(a)	Conditions for High Temperature Reverse Bias Burn-in	19
5(b)	Conditions for Power Burn-in and Operating Life Tests	19
6	Electrical Measurements at Intermediate Points and on Completion of Endurance Testing	21
FIGUE	<u>tes</u>	
1	Parameter Derating Information	7
2	Physical Dimensions	8
3	Functional Diagram	10
4	Circuits for Electrical Measurements	18
5(a)	Electrical Circuit for High Temperature Reverse Bias Burn-in	19
5(h)	Electrical Circuit for Power Burn-in and Operating Life Tests	19

APPENDICES (Applicable to specific Manufacturers only)

None.



Rev. 'A'

PAGÉ

ISSUE 4

5

#### 1. **GENERAL**

#### 1.1 SCOPE

This specification details the ratings, physical and electrical characteristics, test and inspection data for Transistors, Low Power, NPN, based on Types 2N3498, 2N3499, 2N3500 and 2N3501. It shall be read in conjunction with ESA/SCC Generic Specification No. 5000, the requirements of which are supplemented herein.

#### 1.2 COMPONENT TYPE VARIANTS

Variants of the basic type transistor specified herein, which are also covered by this specification, are given in Table 1(a)

#### 1.3 MAXIMUM RATINGS

The maximum ratings, which shall not be exceeded at any time during use or storage, applicable to the transistors specified herein are as scheduled in Table 1(b).

#### 1.4 PARAMETER DERATING INFORMATION

The parameter derating information applicable to the transistors specified herein is shown in Figure 1.

#### 1.5 PHYSICAL DIMENSIONS

The physical dimensions of the transistors specified herein are shown in Figure 2.

#### 1.6 FUNCTIONAL DIAGRAM

The functional diagram, showing lead identification of the transistors specified herein, is shown in Figure 3.

#### 1.7 HIGH TEMPERATURE TEST PRECAUTIONS

For tin-lead plated or solder-dipped lead finish, all tests to be performed at a temperature that exceeds +125°C shall be carried out in 100% inert atmosphere.

#### 2. APPLICABLE DOCUMENTS

The following documents for part of this specification and shall be read in conjunction with it:-

- (a) ESA/SCC Generic Specification No. 5000 for Discrete Semiconductor Components.
- (b) MIL-STD-750, Test Methods and Procedures for Semiconductor Devices.

#### 3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESA/SCC Basic Specification No. 21300 shall apply.



PAGE 6 ISSUE 4

#### TABLE 1(a) - TYPE VARIANTS

VARIANT	BASED ON TYPE	CASE	FIGURE	LEAD MATERIAL AND FINISH		
01	2N3501	TO5	2(a)	D2	(1)	
02	2N3501	TO39	2(b)	D2	(1)	
03	2N3500	TO5	2(a)	D2	(1)	
04	2N3500	TO39	2(b)	D2	(1)	
05	2N3499	TO5	2(a)	D2	(1)	
06	2N3499	TO39	2(b)	D2	(1)	
07	2N3498	TO5	2(a)	D2	(1)	
08	2N3498	TO39	2(b)	D2	(1)	
09	2N3501	TO39	2(b)	E/B = D2, $C = F2$	(2)	
10	2N3501	TO39	2(b)	E/B = D4, C = F4	(2)	
11	2N3499	TO39	2(b)	E/B = D2, $C = F2$	(2)	
12	2N3499	TO39	2(b)	E/B = D4, C = F4	(2)	

#### NOTES

- 1. All leads.
- 2. E = Emitter, B = Base, C = Collector.

#### TABLE 1(b) - MAXIMUM RATINGS

No.	CHARACTERISTICS	SYMBOL	MAXIMUM RATINGS	UNIT	REMARKS
1	Collector-Base Voltage Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12	V <sub>CBO</sub>	150 100	V	·
2	Collector-Emitter Voltage Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12	V <sub>CEO</sub>	150 100	V	
3	Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V	
4	Collector Current Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12	lc	300 500	mA	
5	Power Dissipation 1	P <sub>tot1</sub>	1.0	W	Note 1 T <sub>amb</sub>
6	Power Dissipation 2	P <sub>tot2</sub>	5.0	W	Note 1 T <sub>case</sub>
7	Operating Temperature Range	T <sub>op</sub>	-55 to +200	°C	T <sub>amb</sub>
8	Storage Temperature Range	T <sub>stg</sub>	-65 to +200	°C	
9	Soldering Temperature	T <sub>sol</sub>	+ 260	°C	Note 2

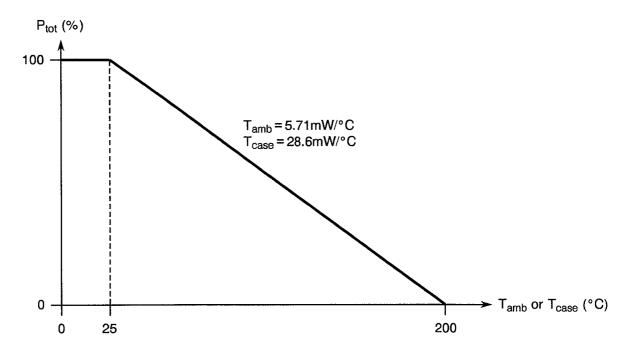
#### **NOTES**

- 1. At  $T_{amb}/T_{case} = +25$ °C. For derating at  $T_{amb}/T_{case} > +25$ °C, see Figure 1.
- 2. Duration 10 seconds maximum at a distance of not less than 1.5mm from the case and the same lead shall not be resoldered until 3 minutes have elapsed.

PAGE

ISSUE 4

#### FIGURE 1 - PARAMETER DERATING INFORMATION



Power Dissipation versus Temperature

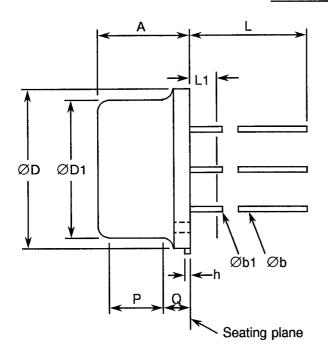


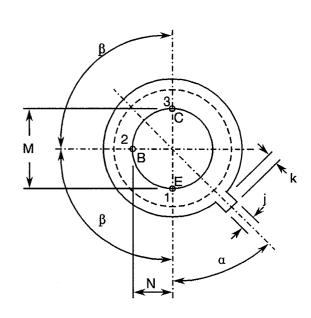
PAGE

ISSUE 4

# FIGURE 2 - PHYSICAL DIMENSIONS

# FIGURE 2(a) - TO5 CASE





SYMBOL	MILLIMETRES		NOTES	
STIVIBOL	MIN.	MAX.	NOTES	
Α	6.10	6.60		
Øb	0.41	0.53	1, 7	
Øb1	0.41	0.48	2, 7	
ØD	8.51	9.40		
ØD1	7.75	8.51		
h	0.23	3.18		
j	0.71	0.86		
k	0.74	1.14	6	
L	38.10	44.45	7	
L1	-	1.27	8	
М	3.591	NOM.	5	
N	1.796	NOM.	5	
Р	2.54	-	3	
Q	-	-	4	
α	45			
β	90	90°		

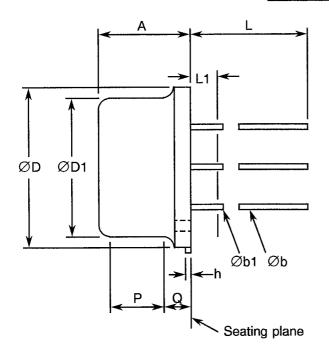
NOTES: See Page 10.

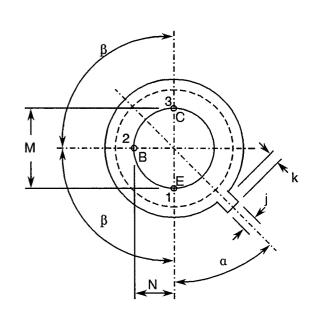
PAGE

ISSUE 4

# FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

# FIGURE 2(b) - TO39 CASE





SYMBOL	MILLIMETRES		NOTES	
STIVIBUL	MIN.	MAX.	NOTES	
Α	6.10	6.60	, ,,	
Øb	0.41	0.53	1, 7	
Øb1	0.41	0.48	2, 7	
ØD	8.51	9.40		
ØD1	7.75	8.51		
h	0.23	3.18		
j	0.71	0.86		
k	0.74	1.14	6	
L	12.70	19.05	7	
L1	-	1.27	8	
M	3.591	NOM.	5	
N	1.796	NOM.	5	
Р	2.54	-	3	
Q	•	-	4	
α	45			
β	90	)°		

**NOTES:** See Page 10.



PAGE 10

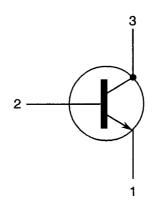
ISSUE 4

#### FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

#### **NOTES**

- 1. Measured in the zone beyond 6.35mm from the seating plane.
- 2. Measured in the zone 1.27mm and 6.35mm from the seating plane.
- 3. Variations on dimension ØD1 in this zone shall not exceed 0.25mm.
- 4. Outline in this zone is not controlled.
- 5. When measured in a gauging plane 1.37(+0.03-0)mm below the seating plane of the transistor, maximum diameter leads shall be within 0.18mm of their true location relative to a maximum width tab. Smaller diameter leads shall fall within the outline of the maximum diameter lead tolerance.
- 6. Measured from the maximum diameter of the actual device.
- 7. All 3 leads.
- 8. Diameter of leads in this zone is not controlled.

#### **FIGURE 3 - FUNCTIONAL DIAGRAM**



- 1. Emitter
- 2. Base
- 3. Collector

#### NOTES

1. The collector is electrically connected to the case.



PAGE 11

ISSUE 4

#### 4. **REQUIREMENTS**

#### 4.1 GENERAL

The complete requirements for procurement of the transistors specified herein are stated in this specification and ESA/SCC Generic Specification No. 5000. Deviations from the Generic Specification, applicable to this specification only, are listed in Para. 4.2.

Deviations from the applicable Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalent to the ESA/SCC requirements are do not affect the components' reliability, are listed in the appendices attached to this specification.

#### 4.2 DEVIATIONS FROM GENERIC SPECIFICATION

#### 4.2.1 Deviations from Special In-process Controls

None.

#### 4.2.2 Deviations from Final Production Tests (Chart II)

None.

#### 4.2.3 Deviations from Burn-in Tests (Chart III)

(a) Para. 7.1.1(a), "High Temperature Reverse Bias (H.T.R.B.)" test: Shall not be performed.

#### 4.2.4 Deviations from Qualification Tests (Chart IV)

None.

#### 4.2.5 Deviations from Lot Acceptance Tests (Chart V)

None.

#### 4.3 MECHANICAL REQUIREMENTS

#### 4.3.1 Dimension Check

The dimensions of the transistors specified herein shall be checked. They shall conform to those shown in Figure 2.

#### 4.3.2 Weight

The maximum weight of the transistors specified herein shall be 1.2 grammes.

#### 4.3.3 <u>Terminal Strength</u>

The requirements for terminal strength testing are specified in Section 9 of ESA/SCC Generic Specification No. 5000. The test conditions shall be as follows:-

Test Condition:

'E' (Lead Fatigue).

Applied Force:

 $2.5 \pm 0.1$  Newtons, 3 bends at  $45^{\circ}$ .

#### 4.4 MATERIALS AND FINISHES

The materials and finishes shall be as specified herein. Where a definite material is not specified, a material which will enable the transistors specified herein to meet the performance requirements of this specification shall be used. Acceptance or approval of any constituent material does not guarantee acceptance of the finished product.



PAGE 12

ISSUE 4

#### 4.4.1 Case

Metal case, hermetically sealed, similar to JEDEC TO5 and TO39.

#### 4.4.2 Lead Material and Finish

The lead material shall be either Type 'D' or Type 'F' with either Type '2' or Type '4' finish in accordance with the requirements of ESA/SCC Basic Specification No. 23500 (see Table 1(a) for Type Variants.

#### 4.5 MARKING

#### 4.5.1 General

The marking of components delivered to this specification shall be in accordance with the requirements of ESA/SCC Basic Specification No. 21700 and the following paragraphs. When the component is too small to accommodate all of the marking specified, as much as space permits shall be marked and the marking information, in full, shall accompany the component in its primary package.

The information to be marked and the order of precedence, shall be as follows:-

- (a) Lead Identification.
- (b) The SCC Component Number.
- (c) Traceability Information.

#### 4.5.2 Lead Identification

Lead identification shall be as shown in Figures 2 and 3.

#### 4.5.3 The SCC Component Number

Each component shall bear the SCC Component Number which shall be constituted and marked as follows:-

	<u>520101301</u> B
Detail Specification Number	
Type Variant (see Table 1(a))	
Testing Level (B or C, as applicable) —	

#### 4.5.4 Traceability Information

Each component shall be marked in respect of traceability information in accordance with the requirements of ESA/SCC Basic Specification No. 21700.

#### 4.6 ELECTRICAL MEASUREMENTS

#### 4.6.1 Electrical Measurements at Room Temperature

The parameters to be measured at room temperature are scheduled in Table 2. Unless otherwise specified, measurements shall be performed at  $T_{amb} = +22 \pm 3$  °C.

#### 4.6.2 Electrical Measurements at High and Low Temperatures

The parameters to be measured at high and low temperatures are scheduled in Table 3.



PAGE 13

ISSUE 4

#### 4.6.3 <u>Circuits for Electrical Measurements</u>

Circuits for use in performing the electrical measurements listed in Tables 2 and 3 of this specification are shown in Figure 4.

#### 4.7 BURN-IN TESTS

#### 4.7.1 Parameter Drift Values

The parameter drift values applicable to burn-in are specified in Table 4 of this specification. Unless otherwise stated, measurements shall be performed at  $T_{amb}$  = +22±3 °C. The parameter drift values ( $\Delta$ ) applicable to the parameters scheduled shall not be exceeded. In addition to these drift value requirements for a given parameter, the appropriate limit value specified in Table 2 shall not be exceeded.

#### 4.7.2 Conditions for High Temperature Reverse Bias Burn-in (Table 5(a))

Not applicable.

#### 4.7.3 Conditions for Power Burn-in

The requirements for power burn-in are specified in Section 7 of ESA/SCC Generic Specification No. 5000. The conditions for power burn-in shall be as specified in Table 5(b) of this specification.

#### 4.7.4 Electrical Circuits for High Temperature Reverse Bias Burn-in (Figure 5(a))

Not applicable.

#### 4.7.5 Electrical Circuits for Power Burn-in

Circuits for use in performing the power burn-in tests are shown in Figure 5(b) of this specification.



PAGE 14

ISSUE 4

# TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - d.c. PARAMETERS

	011101077700	0)/1470	TEST METHOD	TEOT CONDITIONS	LIM	ITS	
No.	CHARACTERISTICS	SYMBOL	MIL-STD- 750	TEST CONDITIONS	MIN	MAX	UNIT
1	Collector-Emitter Sustaining Voltage	V <sub>CEO(Sust)</sub>	3011	I <sub>C</sub> = 10mA I <sub>B</sub> = 0 Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12 Note 1	150 100		V
2	Collector-Base Breakdown Voltage	V <sub>(BR)CEO</sub>	3001	I <sub>C</sub> = 10μA I <sub>E</sub> = 0 Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12	150 100	-	V
3	Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	3026	I <sub>E</sub> = 10μA I <sub>C</sub> = 0	6.0	-	V
4	Collector-Base Cut-off Current	Ісво	3036	Variants 01-02-03-04-09-10 $V_{CB} = 75V$ $I_E = 0$ Variants 05-06-07-08-11-12 $V_{CB} = 50V$ $I_E = 0$	-	50 50	nA
5	Emitter-Base Cut-off Current	I <sub>EBO</sub>	3061	V <sub>CB</sub> = 4.0V I <sub>C</sub> = 0	1	25	nA
6	d.c. Forward Current Transfer Ratio 1	h <sub>FE1</sub>	3076	V <sub>CE</sub> = 10V I <sub>C</sub> = 0.1mA Variants 01-02-05-06-09-10- 11-12 Variants 03-04-07-08 Note 1	35 20		-
7	d.c. Forward Current Transfer Ratio 2	h <sub>FE2</sub>	3076	V <sub>CE</sub> = 10V I <sub>C</sub> = 150mA Variants 01-02-05-06-09-10- 11-12 Variants 03-04-07-08 Note 1	100 40	300 120	•
8	d.c. Forward Current Transfer Ratio 3	h <sub>FE3</sub>	3076	Variants 01-02-09-10 Variants 03-04 $V_{CE} = 10V$ $I_{C} = 300$ mA Variants 05-06-11-12 Variants 07-08 $V_{CE} = 10V$ $I_{C} = 500$ mA Note 1	20 15 20 15	- - -	-

**NOTES:** See Page 16.

PAGE 15

ISSUE 4

# TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - d.c. PARAMETERS (CONT'D)

No.	CHARACTERISTICS	SYMBOL	TEST METHOD	TEST CONDITIONS	LIMITS		UNIT
140.	CHANACTERISTICS	STWIBOL	MIL-STD- 750	TEST CONDITIONS	MIN	MAX	01411
9	Collector-Emitter Saturation Voltage 1	V <sub>CE(SAT)1</sub>	3071	Variants 01-02-03-04-09-10 $I_C$ = 150mA $I_B$ = 15mA		0.4	V
10	Collector-Emitter Saturation Voltage 2	V <sub>CE(SAT)2</sub>	3071	I <sub>C</sub> = 10mA I <sub>B</sub> = 1.0mA Note 1	-	0.2	V
11	Base-Emitter Saturation Voltage 1	V <sub>BE(SAT)1</sub>	3066	Variants 01-02-03-04-09-10 $I_C = 150 \text{mA}$ $I_B = 15 \text{mA}$ Variants 05-06-07-08-11-12 $I_C = 300 \text{mA}$ $I_B = 30 \text{mA}$ Note 1	-	1.2	V
12	Base-Emitter Saturation Voltage 2	V <sub>BE(SAT)2</sub>	3066	I <sub>C</sub> = 10mA I <sub>B</sub> = 1.0mA Note 1	-	0.8	V

**NOTES**: See Page 16.



PAGE 16

ISSUE 4

# TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - a.c. PARAMETERS

		OVANDOL	TEST METHOD	TEST	TEGT COMPITIONS	LIMITS		LINDT
No.	CHARACTERISTICS	SYMBOL	MIL-STD- 750	FIG.	TEST CONDITIONS	MIN	MAX	UNIT
13	Input Capacitance	C <sub>IBO</sub>	3240	-	V <sub>EB</sub> = 0.5V I <sub>C</sub> = 0 f = 100kHz	1	80	pF
14	Output Capacitance	C <sub>OBO</sub>	3236	-	$V_{CB} = 10V$ $I_E = 0$ f = 100kHz Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12		8.0 10	pF
15	a.c. Forward Current Transfer Ratio	h <sub>fe</sub>	3306	-	V <sub>CE</sub> = 10V I <sub>C</sub> = 10mA f = 1.0kHz Variants 01-02-05-06-09-10 Variants 03-04-07-08-11-12	75 50	375 300	-
16	Common-Emitter a.c. Forward Current Transfer Ratio	h <sub>fe</sub>	3306	-	V <sub>CE</sub> = 20V I <sub>C</sub> = 20mA f = 100MHz	1.5	8.0	
17	Gain-Bandwidth Product	f <sub>T</sub>	3621	-	$V_{CE} = 20V$ $I_{C} = 20mA$ f = 100MHz	150	-	MHz
18	Delay Time	t <sub>d</sub>	-	4	Variants 01-02-03-04-09-10 $V_{CC}$ = 100V $V_{BE(OFF)}$ = -2.0V $V_{CC}$ = 66V $V_{BE(OFF)}$ = -2.0V $V_{CC}$ = 0.0V $V_{CC}$	-	40 40	ns
19	Rise Time	t <sub>r</sub>	-	4	I <sub>C</sub> = 150mA I <sub>B1</sub> = 15mA Note 2	-	70	ns
20	Storage Time	t <sub>s</sub>	-	4	Variants 01-02-03-04-09-10 $V_{CC}$ = 100V $I_{C}$ = 150mA Variants 05-06-07-08-11-12 $V_{CC}$ = 66V $V_{BE(OFF)}$ = $-3.8V$ $I_{C}$ = 150mA Note 2	-	900	ns
21	Rise Time	t <sub>f</sub>	-	4	l <sub>B1</sub> = l <sub>B2</sub> ≈ 15mA Note 2	_	240	ns

#### NOTES

- 1. Pulse measurement, pulse length ≤300 $\mu$ s, Duty Cycle ≤2.0%.
- 2. Measurements shall be performed on a sample basis, LTPD7 or less.

PAGE 17

ISSUE 4

# TABLE 3 - ELECTRICAL MEASUREMENTS AT HIGH AND LOW TEMPERATURES

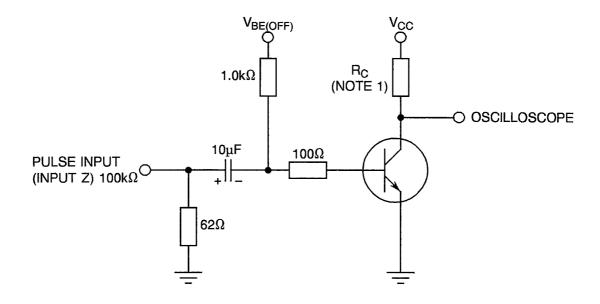
No.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD-750	TEST CONDITIONS	LIMITS		LINUT
					MIN	MAX	UNIT
4	Collector-Base Cut-off Current	Ісво	3036	$T_{amb} = +150 ^{\circ} C$ Variants 01-02-03-04-09-10 $V_{CB} = 75 V$ $I_{E} = 0$ Variants 05-06-07-08-11-12 $V_{CB} = 50 V$ $I_{E} = 0$		50 50	μA
7	d.c. Forward Current Transfer Ratio 2	h <sub>FE2</sub>	3076	T <sub>amb</sub> = -55°C V <sub>CE</sub> = 10V I <sub>C</sub> = 150mA Variants 01-02-05-06-09-10- 11-12 Variants 03-04-07-08 Note 1	50 22		•

NOTES: See Page 16.

PAGE 18

ISSUE 4

### FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS



**INPUT PULSE** 

Duty Cycle  $\leq$ 2%,  $t_r = t_f \leq$ 20ns.

$$\frac{\text{NOTES}}{1. \quad R_{\text{C}}} = \frac{V_{\text{CC}}}{I_{\text{C}}} \quad (\Omega)$$



PAGE 19

ISSUE 4

#### **TABLE 4 - PARAMETER DRIFT VALUES**

No.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITIONS	CHANGE LIMITS (Δ)	UNIT
4	Collector-Base Cut-off Current	Ісво	As per Table 2	As per Table 2	±10 or (1) ±100	nA %
7	d.c. Forward Current Transfer Ratio 2	h <sub>FE2</sub>	As per Table 2	As per Table 2	±15	%
9	Collector-Emitter Saturation Voltage 1	V <sub>CE(SAT)1</sub>	As per Table 2	As per Table 2	±50 or (1) ±15	mV %

#### **NOTES**

1. Whichever is greater, referred to the initial value.

#### TABLE 5(a) - CONDITIONS FOR HIGH TEMPERATURE REVERSE BIAS BURN-IN

Not applicable.

#### TABLE 5(b) - CONDITIONS FOR POWER BURN-IN AND OPERATING LIFE TESTS

No.	CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT
1	Ambient Temperature	T <sub>amb</sub>	+25±3	°C
2	Power Dissipation	P <sub>tot</sub>	1.0	W
3	Collector-Base Voltage	V <sub>CB</sub>	Variants 01-02-03-04-09-10: 100 Variants 05-06-07-08-11-12: 60	V

#### FIGURE 5(a) - ELECTRICAL CIRCUIT FOR HIGH TEMPERATURE REVERSE BIAS BURN-IN

Not applicable.

#### FIGURE 5(b) - ELECTRICAL CIRCUIT FOR POWER BURN-IN AND OPERATING LIFE TESTS

Not applicable.



PAGE 20

ISSUE 4

# 4.8 <u>ENVIRONMENTAL AND ENDURANCE TESTS (CHARTS IV AND V OF ESA/SCC GENERIC SPECIFICATION NO. 5000)</u>

#### 4.8.1 Electrical Measurements on Completion of Environmental Tests

The parameters to be measured on completion of environmental tests are scheduled in Table 2. Unless otherwise stated, the measurements shall be performed at  $T_{amb}$  = +22 ±3 °C.

#### 4.8.2 Electrical Measurements at Intermediate Points and on Completion of Endurance Tests

The parameters to be measured at intermediate points and on completion of endurance tests are scheduled in Table 6 of this specification. Unless otherwise stated, the measurements shall be performed at  $T_{amb}$  = +22 ±3 °C.

#### 4.8.3 Conditions for Operating Life Tests (Part of Endurance Testing)

The requirements for operating life testing are specified in Section 9 of ESA/SCC Generic Specification No. 5000. The conditions for operating life testing shall be the same as specified in Table 5(b) for the burn-in test.

#### 4.8.4 Electrical Circuits for Operating Life Tests

The circuit to be used for performance of the operating life tests shall be the same as shown in Figure 5(b) for the burn-in test.

#### 4.8.5 Conditions for High Temperature Storage Test (Part of Endurance Testing)

The requirements for the high temperature storage test are specified in ESA/SCC Generic Specification No. 5000. The temperature to be applied shall be the maximum storage temperature specified in Table 1(b) of this specification.



PAGE 21

ISSUE 4

# TABLE 6 - ELECTRICAL MEASUREMENTS AT INTERMEDIATE POINTS AND ON COMPLETION OF ENDURANCE TESTING

No.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITIONS	LIMITS		UNIT
					MIN.	MAX.	UNIT
4	Collector-Base Cut-off Current	I <sub>CBO</sub>	As per Table 2	As per Table 2 Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12		50 50	nA
7	d.c. Forward Current Transfer Ratio 2	h <sub>FE2</sub>	As per Table 2	As per Table 2 Variants 01-02-05-06-09-10- 11-12 Variants 03-04-07-08	100 40	300 120	-
9	Collector-Emitter Saturation Voltage 1	V <sub>CE(SAT)1</sub>	As per Table 2	As per Table 2 Variants 01-02-03-04-09-10 Variants 05-06-07-08-11-12	-	0.4 0.6	V